Lattice Semiconductor Corporation - LFSC3GA80E-5FC1704C Datasheet

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	20000
Number of Logic Elements/Cells	80000
Total RAM Bits	5816320
Number of I/O	904
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1704-BCBGA, FCBGA
Supplier Device Package	1704-CFCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga80e-5fc1704c

Table 1-1. LatticeSC Family Selection Guide[1]

Device	SC15	SC25	SC40	SC80	SC115
LUT4s (K)	15	25	40	80	115
sysMEM Blocks (18Kb)	56	104	216	308	424
Embedded Memory (Mbits)	1.03	1.92	3.98	5.68	7.8
Max. Distributed Memory (Mbits)	0.24	0.41	0.65	1.28	1.84
Number of 3.8Gbps SERDES (Max.)	8	16	16	32	32
DLLs	12	12	12	12	12
Analog PLLs	8	8	8	8	8
MACO Blocks	4	6	10	10	12
Package I/O/SERDES Combinations (1mm ball pitch)					
256-ball fpBGA (17 x 17mm)	139/4				
900-ball fpBGA (31 x 31mm)	300/8	378/8			
1020-ball fcBGA (33 x 33mm)[2]		476/16	562/16		
1152-ball fcBGA (35 x 35mm)[3]			604/16	660/16	660/16
1704-ball fcBGA (42.5 x 42.5mm)[3]				904/32	942/32

1. The information in this preliminary data sheet is by definition not final and subject to change. Please consult the Lattice web site and your local Lattice sales office to ensure you have the latest information regarding the specifications for these products as you make critical design decisions.
2. Organic fcBGA converted to organic fcBGA revision 2 per PCN #02A-10.
3. Ceramic fcBGA converted to organic fcBGA per PCN #01A-10.

The LatticeSCM devices add MACO-enabled IP functionality to the base LatticeSC devices. Table 1-2 shows the type and number of each pre-engineered IP core.

Table 1-2. LatticeSCM Family

Device	SCM15	SCM25	SCM40	SCM80	SCM115
flexiMAC Blocks • 1GbE Mode • 10GbE Mode • PCI Express Mode	1	2	2	2	4
SPI4.2 Blocks	1	2	2	2	2
Memory Controller Blocks • DDR/DDR2 DRAM Mode • QDR II/II+ SRAM Mode • RLDRAM I • RLDRAM II CIO/SIO	1	2	2	2	2
Low-Speed CDR Blocks	0	0	2	2	2
PCI Express LTSSM (PHY) Blocks	1	0	2	2	2

Note: See each IP core user's guide for more information about support for specific LatticeSCM devices.

Introduction

The LatticeSC family of FPGAs combines a high-performance FPGA fabric, high-speed SERDES, high-performance I/Os and large embedded RAM in a single industry leading architecture. This FPGA family is fabricated in a state of the art technology to provide one of the highest performing FPGAs in the industry.

This family of devices includes features to meet the needs of today's communication network systems. These features include SERDES with embedded advance PCS (Physical Coding sub-layer), up to 7.8 Mbits of sysMEM embedded block RAM, dedicated logic to support system level standards such as RAPIDIO, SPI4.2, SFI-4, UTOPIA, XGMII and CSIX. The devices in this family feature clock multiply, divide and phase shift PLLs, numerous toggled. There are eight DCS blocks per device, located in pairs at the center of each side. Figure 2-9 illustrates the DCS Block diagram.

Figure 2-9. DCS Block Diagram

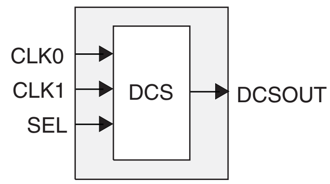
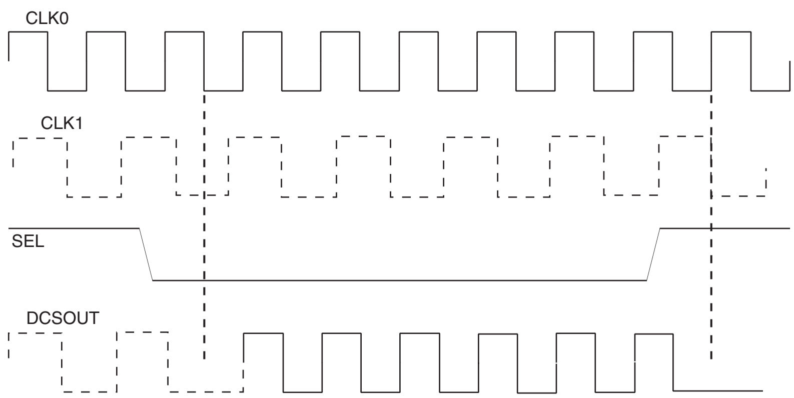


Figure 2-10 shows timing waveforms for one of the DCS operating modes. The DCS block can be programmed to other modes. For more information on the DCS, please see details of additional technical documentation at the end of this data sheet.

Figure 2-10. DCS Waveforms



Clock Boosting

There are programmable delays available in the clock signal paths in the PFU, PIC and EBR blocks. These allow setup and clock-to-output times to be traded to meet critical timing without slowing the system clock. If this feature is enabled then the design tool automatically uses these delays to improve timing performance.

Global Set/Reset

There is a global set/reset (GSR) network on the device that is distributed to all FFs, PLLs, DLLs and other blocks on the device. This GSR network can operate in two modes:

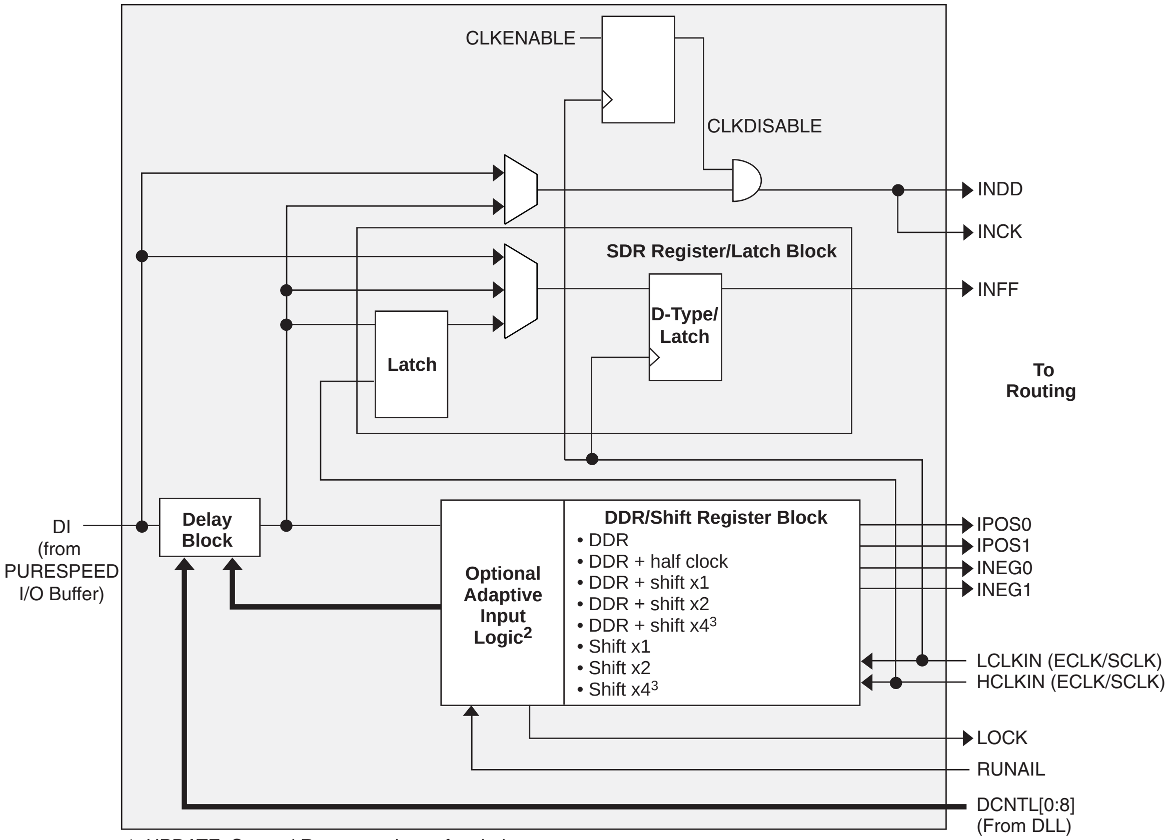
a) asynchronous - no clock is required to get into or out of the reset state.

b) synchronous - The global GSR net is synchronized to a user selected clock. In this mode it continues to be asynchronous to get into the reset state, but is synchronous to get out of the reset state. This allows all registers on the device to become operational in the same clock period. The synchronous GSR goes out of reset in two cycles from the clock edge where the setup time of the FF was met (not from the GSR being released).

sysCLOCK Phase Locked Loops (PLLs)

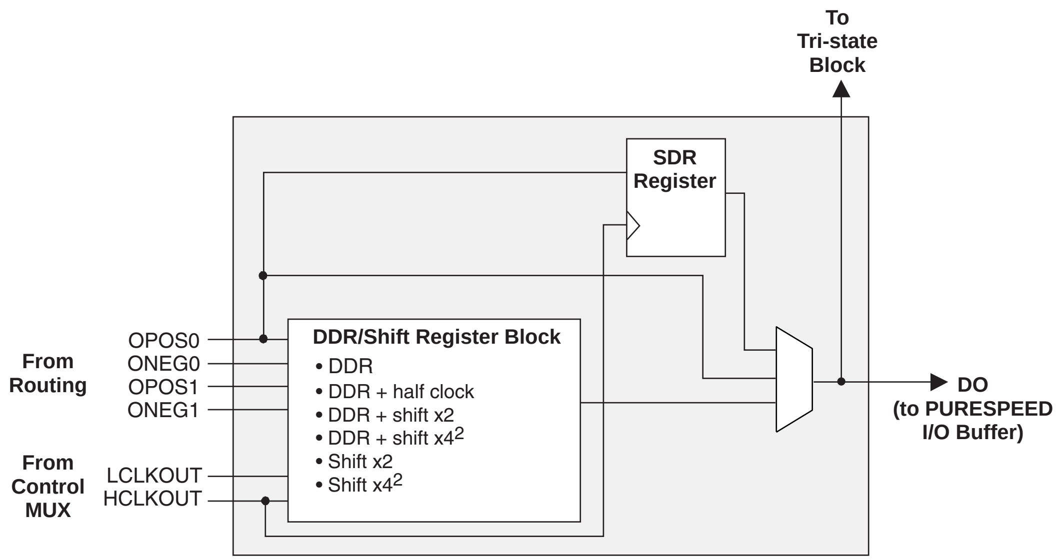
The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider and two clock output dividers. The input divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal.

Figure 2-20. Input Register Block[1]



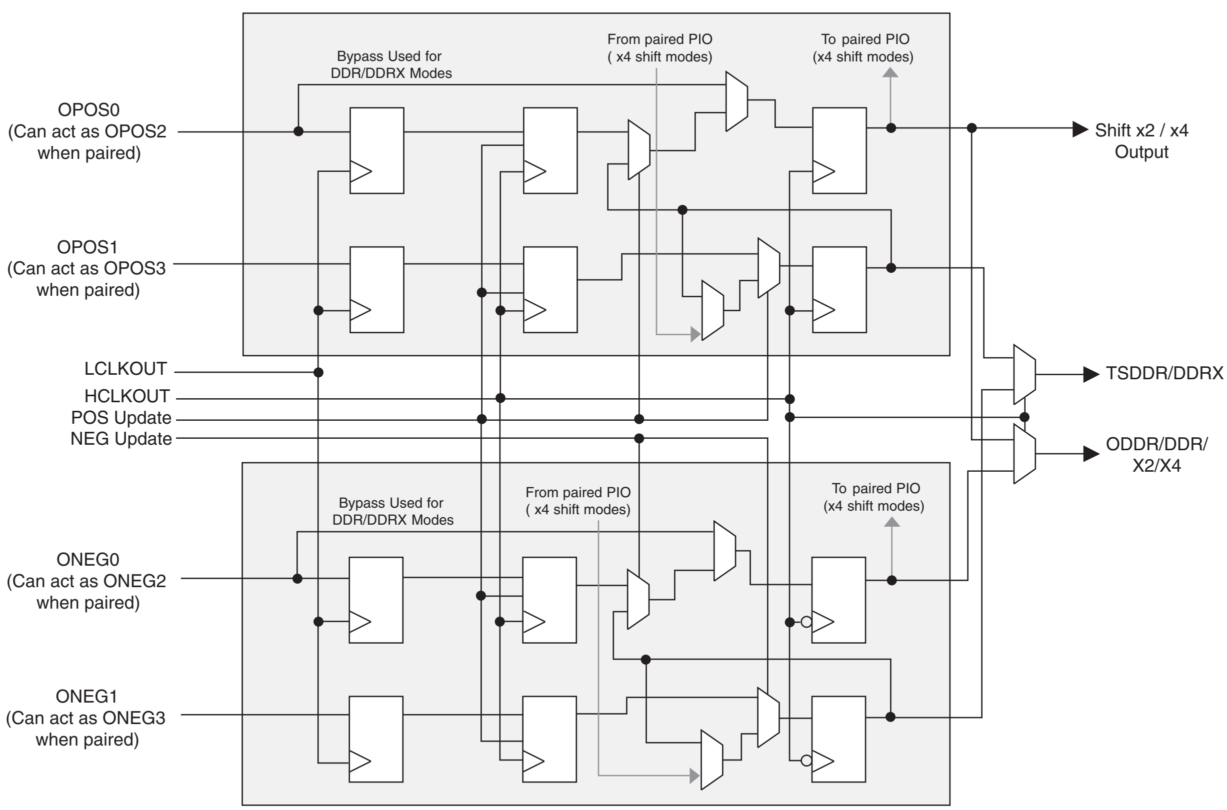
1. UPDATE, Set and Reset not shown for clarity
2. Adaptive input logic is only available in selected PIO
3. By four shift modes utilize DDR/shift register block from paired PIO.
4. CLKDISABLE is used to block the transitions on the DQS pin during post-amble. Its main use is to disable DQS (typically found in DDR memory interfaces) or other clock signals. It can also be used to disable any/all input signals to save power.

Figure 2-22. Output Register Block[1]



Notes:
1. CE, Update, Set and Reset not shown for clarity.
2. By four shift modes utilizes DDR/Shift register block from paired PIO.
3. DDR/Shift register block shared with tristate block.

Figure 2-23. Output/Tristate DDR/Shift Register Block

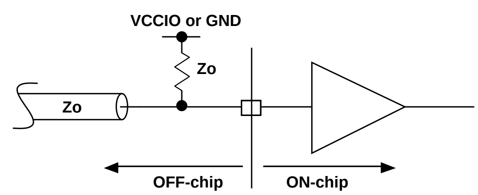
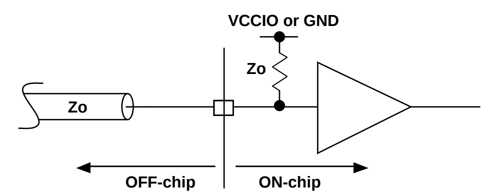
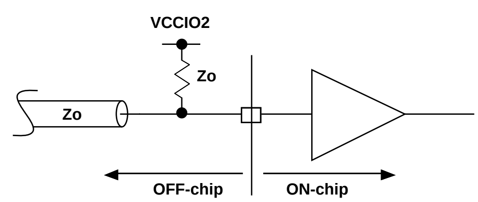
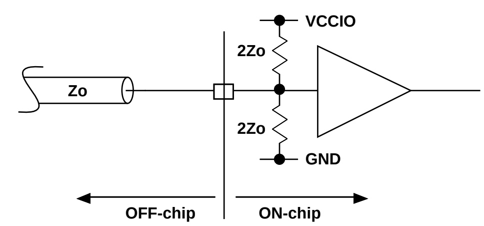
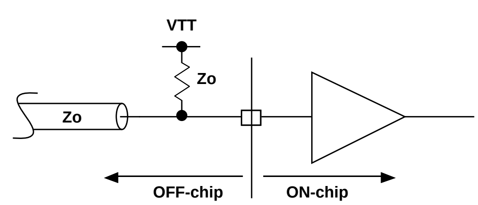
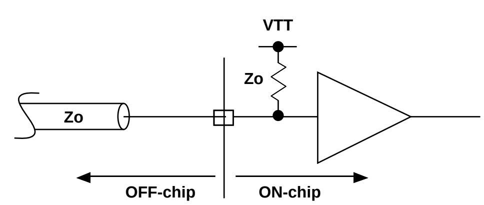


Single Ended Inputs: The SC devices support a number of different termination schemes for single ended inputs:

- Parallel to V_{CCIO} or GND
- Parallel to $V_{CCIO}/2$
- Parallel to V_{TT}

Figure 2-28 shows the single ended input schemes that are supported. The nominal values of the termination resistors are shown in Table 2-9.

Figure 2-28. Input Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Parallel termination to to V_{CCIO}, or parallel to GND receiving end		
Parallel termination to $V_{CCIO}/2$ receiving end		
Parallel termination to V_{TT} at receiving end		

In many situations designers can chose whether to use Thevenin or parallel to V_{TT} termination. The Thevenin approach has the benefit of not requiring a termination voltage to be applied to the device. The parallel to V_{TT} approach consumes less power.

VTT Termination Resources

Each I/O bank, except bank 1, has a number of V_{TT} pins that must be connected if V_{TT} is used. Note V_{TT} pins can sink or source current and the power supply they are connected to must be able to handle the relatively high currents associated with the termination circuits. Note: V_{TT} is not available in all package styles.

On-chip parallel termination to V_{TT} is supported at the receiving end only. On-chip parallel output termination to V_{TT} is not supported.

The V_{TT} internal bus is also connected to the internal V_{CMT} node. Thus in one bank designers can implement either V_{TT} termination or V_{CMT} termination for differential inputs.

DDRII/RLDRAMII Termination Support

The DDR II memory and RLDRAMII (in Bidirection Data mode) standards require that the on-chip termination to V_{TT} be turned on when a pin is an input and off when the pin is an output. The LatticeSC devices contain the required circuitry to support this behavior. For additional detail refer to technical information at the end of the data sheet.

this allows for easy integration with the rest of the system. These capabilities make the LatticeSC ideal for many multiple power supply and hot-swap applications. The maximum current during hot socketing is 4mA. See Hot Socketing Specifications in Chapter 3 of this data sheet.

Power-Up Requirements

To prevent high power supply and input pin currents, each VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies must have a monotonic ramp up time of 75 ms or less to reach its minimum operating voltage. Apart from VCC and VCC12, which have an additional requirement, and VCCIO and VCCAUX, which also have an additional requirement, the VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies can ramp up in any order, with no restriction on the time between them. However, the ramp time for each must be 75 ms or less. Configuration of the device will not proceed until the last power supply has reached its minimum operating voltage.

Additional Requirement for VCC and VCC12:

VCC12 must always be higher than VCC. This condition must be maintained at ALL times, including during power-up and power-down. Note that for 1.2V only operation, it is advisable to source both of these supplies from the same power supply.

Additional Requirement for VCCIO and VCCAUX:

If any VCCIOs are 1.2/1.5/1.8V, then VCCAUX MUST be applied before them. If any VCCIO is 1.2/1.5/1.8V and is powered up before VCCAUX, then when VCCAUX is powered up, it may drag VCCIO up with it as it crosses through the VCCIO value. (Note: If the VCCIO supply is capable of sinking current, as well as the more usual sourcing capability, this behavior is eliminated. However, the amount of current that the supply needs to sink is unknown and is likely to be in the hundreds of milliamps range).

Power-Down Requirements

To prevent high power supply and input pin currents, power must be removed monotonically from either VCC or VCCAUX (and must reach the power-down trip point of 0.5V for VCC, 0.95V for VCCAUX) before power is removed monotonically from VCC12, any of the VCCIOs, or VCCJ. Note that VCC12 can be removed at the same time as VCC, but it cannot be removed earlier. In many applications, VCC and VCC12 will be sourced from the same power supply and so will be removed together. For systems where disturbance of the user pins is a don't care condition, the power supplies can be removed in any order as long as they power down monotonically within 200ms of each other.

Additionally, if any banks have VCCIO=3.3V nominal (potentially banks 1, 4, 5) then VCCIO for those banks must not be lower than VCCAUX during power-down. The normal variation in ramp-up times of power supplies and voltage regulators is not a concern here.

Note: The SERDES power supplies are NOT included in these requirements and have no specific sequencing requirements. However, when using the SERDES with VDDIB or VDDOB that is greater than 1.2V (1.5V nominal for example), the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in the ramp-up times of power supplies and voltage regulators is not a concern here.

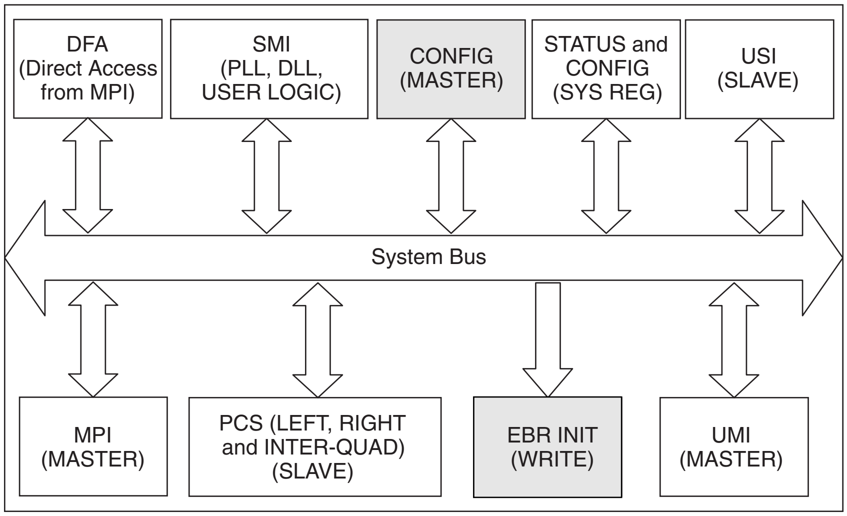
SERDES Power Supply Sequencing Requirements

When using the SERDES with 1.5V VDDIB or VDDOB supplies, the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and the 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in ramp-up times of power supples and voltage regulators is not a concern.

Additional Requirement for SERDES Power Supply

All VCC12 pins need to be connected on all devices independent of functionality used on the device. This analog supply is used by both the RX and TX portions of the SERDES and is used to control the core SERDES logic regardless of the SERDES being used in the design. VDDIB and VDDOB are used as supplies for the terminations on the CML input and output buffers. If a particular channel is not used, these can be UNCONNECTED (floating).

Figure 2-31. LatticeSC System Bus Interfaces



Several interfaces exist between the System Bus and other FPGA elements. The MPI interface acts as a bridge between the external microprocessor bus and System Bus. The MPI may work in an independent clock domain from the System Bus if the System Bus clock is not sourced from the external microprocessor clock. Pipelined operation allows high-speed memory interface to the EBR and peripheral access without the requirement for additional cycles on the bus. Burst transfers allow optimal use of the memory interface by giving advance information of the nature of the transfers.

Details for the majority of the peripherals can be found in the associated technical documentation, see details at the end of this data sheet. Additional details of the MPI are provided below.

Microprocessor Interface (MPI)

The LatticeSC family devices have a dedicated synchronous MPI function block. The MPI is programmable to operate with PowerPC/PowerQUICC MPC860/MPC8260 series microprocessors. The MPI implements an 8-, 16-, or 32-bit interface with 1-bit, 2-bit, or 4-bit parity to the host processor (PowerPC) that can be used for configuration and read-back of the FPGA as well as for user-defined data processing and general monitoring of FPGA functions.

The control portion of the MPI is available following power-up of the FPGA if the mode pins specify MPI mode, even if the FPGA is not yet configured. The width of the data port is selectable among 8-, 16-, or 32-bit and the parity bus can be 1-, 2-, or 4-bit. In configuration mode the data and parity bus width are related to the state of the M[0:3] mode pins. For post-configuration use, the MPI must be included in the configuration bit stream by using an MPI library element in your design from the ispLEVER primitive library, or by setting the bit of the MPI configuration control register prior to the start of configuration. The user can also enable and disable the parity bus through the configuration bit stream. These pads can be used as general I/O when they are not needed for MPI use.

The MPI block also provides the capability to interface directly to the FPGA fabric with a databus after configuration.The bus protocol is still handled by the MPI block but the direct FPGA access allows high-speed block data transfers such as DMA transactions. Figure 2-32 shows one of the ways a PowerPC is connected to MPI.

LatticeSC/M Family Timing Adders (Continued)

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
GTLPLUS15	GTLPLUS15	-0.013	-0.017	0.012	0.004	0.037	0.024	ns
GTL12	GTL12	-0.063	-0.071	-0.007	-0.048	0.056	-0.032	ns
Output Adjusters								
LVDS	LVDS	0.708	0.854	0.856	1.021	1.005	1.189	ns
RSDS	RSDS	0.708	0.854	0.856	1.021	1.005	1.189	ns
BLVDS25	BLVDS	-0.129	0.05	-0.136	0.069	-0.136	0.083	ns
MLVDS25	MLVDS	-0.059	0.059	-0.057	0.096	-0.054	0.133	ns
LVPECL33	LVPECL	-0.334	-0.181	-0.325	-1.389	-0.315	-2.598	ns
HSTL18_I	HSTL_18 class I	0.132	0.209	0.153	0.24	0.175	0.272	ns
HSTL18_II	HSTL_18 class II	0.24	0.176	0.268	0.255	0.298	0.333	ns
HSTL18D_I	Differential HSTL 18 class I	0.132	0.209	0.153	0.24	0.175	0.272	ns
HSTL18D_II	Differential HSTL 18 class II	0.24	0.176	0.268	0.255	0.298	0.333	ns
HSTL15_I	HSTL_15 class I	0.096	0.172	0.112	0.198	0.129	0.224	ns
HSTL15_II	HSTL_15 class II	0.208	0.131	0.233	0.203	0.259	0.275	ns
HSTL15D_I	Differential HSTL 15 class I	0.096	0.172	0.112	0.198	0.129	0.224	ns
HSTL15D_II	Differential HSTL 15 class II	0.208	0.131	0.233	0.203	0.259	0.275	ns
SSTL33_I	SSTL_3 class I	0.133	0.177	0.11	0.166	0.088	0.154	ns
SSTL33_II	SSTL_3 class II	0.173	0.247	0.164	0.253	0.156	0.258	ns
SSTL33D_I	Differential SSTL_3 class I	0.133	0.177	0.11	0.166	0.088	0.154	ns
SSTL33D_II	Differential SSTL_3 class II	0.173	0.247	0.164	0.253	0.156	0.258	ns
SSTL25_I	SSTL_2 class I	0.215	0.125	0.239	0.228	0.264	0.331	ns
SSTL25_II	SSTL_2 class II	0.277	0.181	0.311	0.284	0.345	0.387	ns
SSTL25D_I	Differential SSTL_2 class I	0.215	0.125	0.239	0.228	0.264	0.331	ns
SSTL25D_II	Differential SSTL_2 class II	0.277	0.181	0.311	0.284	0.345	0.387	ns
SSTL18_I	SSTL_2 class I	0.16	0.081	0.179	0.173	0.199	0.265	ns
SSTL18_II	SSTL_2 class II	0.238	0.15	0.263	0.244	0.295	0.338	ns
SSTL18D_I	Differential SSTL_2 class I	0.16	0.081	0.179	0.173	0.199	0.265	ns
SSTL18D_II	Differential SSTL_2 class II	0.238	0.15	0.263	0.244	0.295	0.338	ns
LVTTL33_8mA	LVTTL 8mA drive	-0.346	-0.165	-0.496	-0.296	-0.646	-0.428	ns
LVTTL33_16mA	LVTTL 16mA drive	-0.11	-0.18	-0.218	-0.32	-0.325	-0.46	ns
LVTTL33_24mA	LVTTL 24mA drive	-0.012	-0.18	-0.099	-0.321	-0.185	-0.463	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	-0.346	-0.165	-0.496	-0.296	-0.646	-0.428	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive	-0.11	-0.18	-0.218	-0.32	-0.325	-0.46	ns
LVCMOS33_24mA	LVCMOS 3.3 24mA drive	-0.012	-0.18	-0.099	-0.321	-0.185	-0.463	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	-0.174	0.004	-0.195	0.002	-0.215	0	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0	0	0	0	0	0	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.094	-0.025	0.107	0.096	0.12	0.216	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive	0.145	-0.054	0.162	0.063	0.181	0.179	ns
LVCMOS25_OD	LVCMOS 2.5 open drain	0.073	-0.125	0.081	-0.081	0.091	-0.09	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	-0.278	-0.099	-0.312	-0.115	-0.345	-0.131	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	-0.073	-0.078	-0.078	-0.084	-0.083	-0.089	ns

LatticeSC/M sysCONFIG Port Timing

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
General Configuration Timing				
t_{SMODE}	M[3:0] Setup Time to INITN High	0	—	ns
t_{HMODE}	M[3:0] Hold Time from INITN High	600	—	ns
t_{RW}	RESETN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
t_{PGW}	PROGRAMN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
$f_{ESB\_CLK\_FRQ}$	System Bus ESB_CLK Frequency (No Wait States)	—	133	MHz
sysCONFIG Master Parallel Configuration Mode				
t_{SMB}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMB}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMB}	RCLK Low Time (Non-compressed Bitstreams)	0.5	0.5	CCLK periods
	RCLK Low Time (Compressed Bitstreams)	0.5	7.5	CCLK periods
t_{CHMB}	RCLK High Time	0.5	0.5	CCLK periods
sysCONFIG SPI Port				
t_{CFGX}	INITN High to CSCK Low	—	80	ns
t_{CSSPI}	INITN High to CSSPIN Low	0	2	µs
t_{SCK}	CSCK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CSCK Low to Output Valid	—	15	ns
t_{CSPID}	CSSPIN Low to CSCK high Setup Time	—	15	ns
f_{MAXSPI}	Max CCLK Frequency - SPI Flash Fast Read Opcode (0x0B) (SPIFASTN=0)	—	50	MHz
t_{SUSPI}	SOSPI/D0 Data Setup Time Before CSCK	7	—	ns
t_{HSPI}	SOSPI/D0 Data Hold Time After CSCK	2	—	ns
	Master Clock Frequency	Selected value - 30%	Selected value + 30%	MHz
	Duty Cycle	40	60	%
sysCONFIG Master Serial Configuration Mode				
t_{SMS}	DIN Setup Time	4.4	—	ns
t_{HMS}	DIN Hold Time	0	—	ns
f_{CMS}	CCLK Frequency (No Divider)	90	190	MHz
f_{C_DIV}	CCLK Frequency (Div 128)	0.70	1.48	MHz
t_D	CCLK to DOUT Delay	—	7.5	ns
sysCONFIG Master Parallel Configuration Mode				
t_{AVMP}	RCLK to Address Valid	—	10	ns
t_{SMP}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMP}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMP}	RCLK Low Time (Non-compressed Bitstream)	7.5	7.5	CCLK periods
	RCLK Low Time (Compressed Bitstream)	0.5	63.5	
t_{CHMP}	RCLK High Time	0.5	0.5	CCLK periods
t_{DMP}	CCLK to DOUT	—	7.5	ns

LatticeSC/M sysCONFIG Port Timing (Continued)

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
sysCONFIG Asynchronous Peripheral Configuration Mode				
t_{WRAP}	WRN, CS0N and CS1 Pulse Width	5	-	ns
t_{SAP}	D[7:0] Setup Time	1.5	-	ns
t_{RDYAP}	RDY Delay	—	8	ns
t_{BAP}	RDY Low	1	8	CCLK periods
t_{WR2AP}	Earliest WRN After RDY Goes High	0	—	ns
t_{DENAP}	RDN to D[7:0] Enable/Disable	—	7.5	ns
t_{DAP}	CCLK to DOUT	—	7.5	ns
sysCONFIG Slave Serial Configuration Mode				
t_{SSS}	DIN Setup Time	5.2	—	ns
t_{HSS}	DIN Hold Time	0	—	ns
t_{CHSS}	CCLK High Time	3.75	—	ns
t_{CLSS}	CCLK Low Time	3.75	—	ns
f_{CSS}	CCLK Frequency	—	150	MHz
t_{DSS}	CCLK to DOUT	—	7.5	ns
sysCONFIG Slave Parallel Configuration Mode				
t_{S1SP}	CS0N, CS1, WRN Setup Time	5.2	—	ns
t_{H1SP}	CS0N, CS1, WRN Hold Time	0	—	ns
t_{S2SP}	D[7:0] Setup Time	5.2	—	ns
t_{H2SP}	D[7:0] Hold Time	0	—	ns
t_{CHSP}	CCLK High Time	3.75	—	ns
t_{CL}	CCLK Low Time	3.75	—	ns
f_{CSP}	CCLK Frequency	—	150	MHz

sysCONFIG MPI Port

Parameter	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{MPICTRL\_SET}$	MPI Control (MPCSTRBN, MPCWRN, MPCCLK, etc.) to MPCCLK Setup Time	4.9	—	5.2	—	5.5	—	ns
t_{MPIADR_SET}	MPI Address to MPCCLK Setup Time	3.9	—	4.2	—	4.5	—	ns
t_{MPIDAT_SET}	MPI Write Data to MPCCLK Setup Time	4.9	—	5.2	—	5.5	—	ns
$t_{MPIDPAR\_SET}$	MPI Write Parity Data to MPCCLK Setup Time	3.9	—	4.2	—	4.5	—	ns
t_{MPI_HLD}	All Hold Times	0	—	0	—	0	—	ns
$t_{MPICTRL\_DEL}$	MPCCLK to MPI Control (MPCTA, MPC-TEA, MPCRETRY)	—	5.6	—	6.7	—	8.7	ns
t_{MPIDAT_DEL}	MPCCLK to MPI Data	—	5.6	—	6.7	—	8.7	ns
$t_{MPIDPAR\_DEL}$	MPCCLK to MPI Parity Data	—	4.9	—	5.7	—	7.7	ns
$f_{MPI\_CLK\_FRQ}$	MPCCLK Frequency	—	100	—	83	—	66	MHz

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2] (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
F14	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
E15	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
E14	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
D9	VCCJ	-	
C16	TDO	-	TDO
B15	TMS	-	
B16	TCK	-	
E13	TDI	-	
C14	PROGRAMN	1	
C15	CCLK	1	
A15	PT43D	1	HDC/SI
A14	PT43C	1	LDCN/SCS
B14	PT41A	1	CS1
E12	PT39B	1	CS0N
D13	PT39A	1	RDN
D12	PT37D	1	WRN
E10	PT37C	1	D7
C11	PT37B	1	D6
D10	PT37A	1	D5
A13	PT36D	1	D4
B12	PT36C	1	D3
A12	PT35B	1	D2
C12	PT35A	1	D1
A11	PT33B	1	D0
B11	PT33A	1	QOUT/CEON
E9	PT32D	1	VREF2_1
E8	PT32B	1	DOUT
D8	PT28C	1	BUSYN/RCLK/SCK
A10	PT27B	1	PCLKC1_0
C10	PT27A	1	PCLKT1_0
E7	PT21C	1	VREF1_1
C9	A_VDDIB3_L	-	
A9	A_HDINP3_L	-	PCS 360 CH 3 IN P
B9	A_HDINN3_L	-	PCS 360 CH 3 IN N
A8	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
B8	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
C8	A_VDDOB3_L	-	
B7	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
C7	A_VDDOB2_L	-	
A7	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
B6	A_HDINN2_L	-	PCS 360 CH 2 IN N
A6	A_HDINP2_L	-	PCS 360 CH 2 IN P
C6	A_VDDIB2_L	-	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B29	NC	-		NC	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M15 and LatticeSC/M25 in a 900-pin package supports a 16-bit MPI interface.

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B30	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
D30	A_VDDOB0_L	-		A_VDDOB0_L	-	
A30	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
C31	A_HDINN0_L	-	PCS 360 CH 0 IN N	A_HDINN0_L	-	PCS 360 CH 0 IN N
C32	A_HDINP0_L	-	PCS 360 CH 0 IN P	A_HDINP0_L	-	PCS 360 CH 0 IN P
B31	A_VDDIB0_L	-		A_VDDIB0_L	-	
AL25	NC	-		PB26A	5	
AL24	NC	-		PB26B	5	
AG27	NC	-		PB26C	5	
AH27	NC	-		PB26D	5	
AM25	NC	-		PB27A	5	
AM24	NC	-		PB27B	5	
AL9	NC	-		PB62A	4	
AL8	NC	-		PB62B	4	
AK9	NC	-		PB63A	4	
AJ9	NC	-		PB63B	4	
AG10	NC	-		PB63C	4	
AG11	NC	-		PB63D	4	
J30	NC	-		PL26A	7	
H30	NC	-		PL26B	7	
M28	NC	-		PL26C	7	
N28	NC	-		PL26D	7	
J32	NC	-		PL27A	7	
J31	NC	-		PL27B	7	
N26	NC	-		PL27C	7	
N27	NC	-		PL27D	7	
K31	NC	-		PL29A	7	
K32	NC	-		PL29B	7	
P25	NC	-		PL29C	7	
P26	NC	-		PL29D	7	
L27	NC	-		PL22C	7	
L28	NC	-		PL22D	7	
M29	NC	-		PL30A	7	
L29	NC	-		PL30B	7	
M30	NC	-		PL31A	7	
L30	NC	-		PL31B	7	
L31	NC	-		PL34A	7	
M31	NC	-		PL34B	7	
AA29	NC	-		PL56A	6	
AA30	NC	-		PL56B	6	
AB31	NC	-		PL57A	6	
AA31	NC	-		PL57B	6	
AG30	NC	-		PL57C	6	
AG29	NC	-		PL57D	6	
AB29	NC	-		PL58A	6	
AB30	NC	-		PL58B	6	
Y25	NC	-		PL58C	6	
AA25	NC	-		PL58D	6	
AA8	NC	-		PR58D	3	
Y8	NC	-		PR58C	3	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

	LFSC/M40			LFSC/M80		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AG18	PB42C	5		PB61C	5	
AF18	PB42D	5		PB61D	5	
AP19	PB43A	5		PB63A	5	
AP18	PB43B	5		PB63B	5	
AJ18	PB43C	5		PB63C	5	
AH18	PB43D	5		PB63D	5	
AP17	PB45A	4		PB65A	4	
AP16	PB45B	4		PB65B	4	
AJ17	PB45C	4		PB65C	4	
AH17	PB45D	4		PB65D	4	
AN17	PB46A	4		PB66A	4	
AN16	PB46B	4		PB66B	4	
AE17	PB46C	4		PB66C	4	
AD17	PB46D	4		PB66D	4	
AK17	PB47A	4		PB67A	4	
AK16	PB47B	4		PB67B	4	
AG17	PB47C	4		PB67C	4	
AF17	PB47D	4		PB67D	4	
AM16	PB49A	4		PB69A	4	
AM15	PB49B	4		PB69B	4	
AJ15	PB49C	4		PB69C	4	
AJ14	PB49D	4		PB69D	4	
AL16	PB50A	4		PB70A	4	
AL15	PB50B	4		PB70B	4	
AG16	PB50C	4		PB70C	4	
AF16	PB50D	4		PB70D	4	
AP15	PB51A	4		PB71A	4	
AP14	PB51B	4		PB71B	4	
AH15	PB51C	4		PB71C	4	
AH14	PB51D	4		PB71D	4	
AN15	PB53A	4	PCLKT4_2	PB74A	4	PCLKT4_2
AN14	PB53B	4	PCLKC4_2	PB74B	4	PCLKC4_2
AE16	PB53C	4	PCLKT4_7	PB74C	4	PCLKT4_7
AD16	PB53D	4	PCLKC4_7	PB74D	4	PCLKC4_7
AK15	PB54A	4	PCLKT4_1	PB75A	4	PCLKT4_1
AK14	PB54B	4	PCLKC4_1	PB75B	4	PCLKC4_1
AG15	PB54C	4	PCLKT4_6	PB75C	4	PCLKT4_6
AG14	PB54D	4	PCLKC4_6	PB75D	4	PCLKC4_6
AM13	PB55A	4	PCLKT4_0	PB77A	4	PCLKT4_0
AM12	PB55B	4	PCLKC4_0	PB77B	4	PCLKC4_0
AJ12	PB55C	4	VREF2_4	PB77C	4	VREF2_4
AJ11	PB55D	4		PB77D	4	
AL13	PB57A	4	PCLKT4_5	PB79A	4	PCLKT4_5
AL12	PB57B	4	PCLKC4_5	PB79B	4	PCLKC4_5
AH12	PB57C	4		PB79C	4	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

	LFSC/M40			LFSC/M80		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
K20	GND	-		GND	-	
K23	GND	-		GND	-	
K26	GND	-		GND	-	
K28	GND	-		GND	-	
K6	GND	-		GND	-	
K9	GND	-		GND	-	
L12	GND	-		GND	-	
L32	GND	-		GND	-	
L4	GND	-		GND	-	
M10	GND	-		GND	-	
M17	GND	-		GND	-	
M24	GND	-		GND	-	
N29	GND	-		GND	-	
N7	GND	-		GND	-	
P15	GND	-		GND	-	
P20	GND	-		GND	-	
P3	GND	-		GND	-	
P31	GND	-		GND	-	
R10	GND	-		GND	-	
R14	GND	-		GND	-	
R16	GND	-		GND	-	
R19	GND	-		GND	-	
R21	GND	-		GND	-	
R26	GND	-		GND	-	
T15	GND	-		GND	-	
T17	GND	-		GND	-	
T18	GND	-		GND	-	
T20	GND	-		GND	-	
T28	GND	-		GND	-	
T6	GND	-		GND	-	
U16	GND	-		GND	-	
U19	GND	-		GND	-	
U23	GND	-		GND	-	
U32	GND	-		GND	-	
U4	GND	-		GND	-	
V12	GND	-		GND	-	
V16	GND	-		GND	-	
V19	GND	-		GND	-	
V3	GND	-		GND	-	
V31	GND	-		GND	-	
W15	GND	-		GND	-	
W17	GND	-		GND	-	
W18	GND	-		GND	-	
W20	GND	-		GND	-	
W29	GND	-		GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AC24	GND	-		GND	-	
AC26	GND	-		GND	-	
AC35	GND	-		GND	-	
AC8	GND	-		GND	-	
AD12	GND	-		GND	-	
AD16	GND	-		GND	-	
AD18	GND	-		GND	-	
AD20	GND	-		GND	-	
AD23	GND	-		GND	-	
AD25	GND	-		GND	-	
AD27	GND	-		GND	-	
AD31	GND	-		GND	-	
AE17	GND	-		GND	-	
AE19	GND	-		GND	-	
AE24	GND	-		GND	-	
AE26	GND	-		GND	-	
AE3	GND	-		GND	-	
AE39	GND	-		GND	-	
AF18	GND	-		GND	-	
AF20	GND	-		GND	-	
AF23	GND	-		GND	-	
AF25	GND	-		GND	-	
AF36	GND	-		GND	-	
AF7	GND	-		GND	-	
AG11	GND	-		GND	-	
AG16	GND	-		GND	-	
AG19	GND	-		GND	-	
AG24	GND	-		GND	-	
AG27	GND	-		GND	-	
AG32	GND	-		GND	-	
AH15	GND	-		GND	-	
AH28	GND	-		GND	-	
AH4	GND	-		GND	-	
AH40	GND	-		GND	-	
AJ35	GND	-		GND	-	
AJ8	GND	-		GND	-	
AK12	GND	-		GND	-	
AK31	GND	-		GND	-	
AL13	GND	-		GND	-	
AL19	GND	-		GND	-	
AL24	GND	-		GND	-	
AL3	GND	-		GND	-	
AL30	GND	-		GND	-	
AL39	GND	-		GND	-	
AM16	GND	-		GND	-	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA80E-7FC1152C[1]	-7	Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-6FC1152C[1]	-6	Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-5FC1152C[1]	-5	Ceramic fcBGA	1152	COM	80.1
LFSC3GA80E-7FF1152C	-7	Organic fcBGA	1152	COM	80.1
LFSC3GA80E-6FF1152C	-6	Organic fcBGA	1152	COM	80.1
LFSC3GA80E-5FF1152C	-5	Organic fcBGA	1152	COM	80.1
LFSC3GA80E-7FC1704C[1]	-7	Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-6FC1704C[1]	-6	Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-5FC1704C[1]	-5	Ceramic fcBGA	1704	COM	80.1
LFSC3GA80E-7FF1704C	-7	Organic fcBGA	1704	COM	80.1
LFSC3GA80E-6FF1704C	-6	Organic fcBGA	1704	COM	80.1
LFSC3GA80E-5FF1704C	-5	Organic fcBGA	1704	COM	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA80EP1-7FC1152C[1]	-7	Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-6FC1152C[1]	-6	Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-5FC1152C[1]	-5	Ceramic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-7FF1152C	-7	Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-6FF1152C	-6	Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-5FF1152C	-5	Organic fcBGA	1152	COM	80.1
LFSCM3GA80EP1-7FC1704C[1]	-7	Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-6FC1704C[1]	-6	Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-5FC1704C[1]	-5	Ceramic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-7FF1704C	-7	Organic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-6FF1704C	-6	Organic fcBGA	1704	COM	80.1
LFSCM3GA80EP1-5FF1704C	-5	Organic fcBGA	1704	COM	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA115E-6FC1152C[1]	-6	Ceramic fcBGA	1152	COM	115.2
LFSC3GA115E-5FC1152C[1]	-5	Ceramic fcBGA	1152	COM	115.2
LFSC3GA115E-6FF1152C	-6	Organic fcBGA	1152	COM	115.2
LFSC3GA115E-5FF1152C	-5	Organic fcBGA	1152	COM	115.2
LFSC3GA115E-6FC1704C[1]	-6	Ceramic fcBGA	1704	COM	115.2
LFSC3GA115E-5FC1704C[1]	-5	Ceramic fcBGA	1704	COM	115.2
LFSC3GA115E-6FF1704C	-6	Organic fcBGA	1704	COM	115.2
LFSC3GA115E-5FF1704C	-5	Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Industrial

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA15E-6F256I	-6	fpBGA	256	IND	15.2
LFSC3GA15E-5F256I	-5	fpBGA	256	IND	15.2
LFSC3GA15E-6F900I	-6	fpBGA	900	IND	15.2
LFSC3GA15E-5F900I	-5	fpBGA	900	IND	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA15EP1-6F256I	-6	fpBGA	256	IND	15.2
LFSCM3GA15EP1-5F256I	-5	fpBGA	256	IND	15.2
LFSCM3GA15EP1-6F900I	-6	fpBGA	900	IND	15.2
LFSCM3GA15EP1-5F900I	-5	fpBGA	900	IND	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA25E-6F900I	-6	fpBGA	900	IND	25.4
LFSC3GA25E-5F900I	-5	fpBGA	900	IND	25.4
LFSC3GA25E-6FF1020I[1]	-6	Organic fcBGA	1020	IND	25.4
LFSC3GA25E-5FF1020I[1]	-5	Organic fcBGA	1020	IND	25.4
LFSC3GA25E-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	25.4
LFSC3GA25E-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA25EP1-6F900I	-6	fpBGA	900	IND	25.4
LFSCM3GA25EP1-5F900I	-5	fpBGA	900	IND	25.4
LFSCM3GA25EP1-6FF1020I[1]	-6	Organic fcBGA	1020	IND	25.4
LFSCM3GA25EP1-5FF1020I[1]	-5	Organic fcBGA	1020	IND	25.4
LFSCM3GA25EP1-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	25.4
LFSCM3GA25EP1-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-6FF1020I[1]	-6	Organic fcBGA	1020	IND	40.4
LFSC3GA40E-5FF1020I[1]	-5	Organic fcBGA	1020	IND	40.4
LFSC3GA40E-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	40.4
LFSC3GA40E-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	40.4
LFSC3GA40E-6FC1152I[2]	-6	Ceramic fcBGA	1152	IND	40.4
LFSC3GA40E-5FC1152I[2]	-5	Ceramic fcBGA	1152	IND	40.4
LFSC3GA40E-6FF1152I	-6	Organic fcBGA	1152	IND	40.4
LFSC3GA40E-5FF1152I	-5	Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

LatticeSC/M Family Data Sheet Revision History

December 2011 **Data Sheet DS1004**

Date	Version	Section	Change Summary
February 2006	01.0	—	Initial release.
March 2006	01.1	Introduction	SC25 1020 I/O count changed to 476.
		Architecture	Changed ROM 16X4 to ROM 16X2.
			Changed “X2 or X4” to “DIV2 or DIV4”.
			Added Global Set/Reset Section.
		DC and Switching Characteristics	Added notes 5 and 6 to Recommended Operating Conditions table.
			Added Power Supply Ramp Rates table.
			Removed -5 and -6 speed grades from Typical Building Block Performance table.
			Added Input Delay Timing table.
			Added Synchronous GSR Timing table.
		Pinout Information	Expanded PROBE_VCC and PROBE_GND description.
			Removed A-RXREFCLKP_[L/R] from Signal Description table.
			Added RESP_[ULC/URC] to Signal Description table.
			Added notes 1 and 2 to Signal Description table.
			Changed number of NCs to 28.
			Changed number of SERDES (signal + power supply) to 74.
			Removed RESP balls from NC list (B2, C2, B29, C29).
			Added note to VTT table.
			Changed RxRefclk (B2 and C2) to NC.
			Added RESP_ULC.
			Added RESP_URC.
			Changed RxRefclk (B29 and C29) to NC.
June 2006	01.2	Introduction	Changed SERDES min bandwidth from 622 Mbps to 600 Mbps.
			Changed max SERDES bandwidth from 3.4 Gbps to 3.8 Gbps.
			Corrected number of package I/Os for the SC80 and SC115 1704 pin packages.
			Updated speed performance for typical functions with ispLEVER 6.0 values.
		Architecture	Changed “When these pins are not used they should be left unconnected.” with “Unused VTT pins should be connected to GND if the internal or external VCMT function is not used in the bank. If the internal or external VCMT function for differential input termination is used, the VTT pins should be unconnected and allowed to float.”
			Added “SERDES Power Supply Sequencing Requirements” section.
			Changed total bandwidth per quad from 13.6 Gbps to 15.2 Gbps.
			Added the accuracy of the temperature-sensing diode to be typically +/-10 °C. Also referred to a temperature-sensing diode application note for more information.
		DC and Switching Characteristics	Changed “CTAP” to “internal or external VCMT”.
			Changed VCC12 parameter to include VDDP, VDDTX and VDDRX.
			Changed typical values to match ispLEVER 6.0 Power Calculator.

Date	Version	Section	Change Summary
March 2007 (cont.)	01.5 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Internal Timing Parameters with ispLEVER 6.1 SP1 results.
			Updated t_{FDEL} and t_{CDEL} specifications.
			Updated LatticeSC Family Timing Adders with ispLEVER 6.1 SP1 results.
			Updated PLL specifications to expand frequency range down to 2 MHz and break out jitter for the different ranges.
			Added footnote to sysCLOCK PLL Timing table specifying the conditions for the jitter measurements.
			Added t_{DLL} specification to sysCLOCK DLL Timing table.
			Added footnote to sysCLOCK DLL Timing table specifying the conditions for the jitter measurements.
			Added sysCONFIG Master Parallel Configuration Mode and sysCONFIG SPI Port to LatticeSC sysCONFIG Port Timing table.
		Pin Information	Updated Pin Information Summary with SC40 information.
			Updated LFSC25 Logic Signal Connections: FF1020 with SC40 information.
			Updated LFSC80 Logic Signal Connections: FC1152 with SC40 information.
August 2007	01.6	General	Changed references of "HDC" to "HDC/SI".
			Changed references of "LDCN" to "LDCN/SCS".
			Changed references of "BUSYN/RCLK" to "BUSYN/RCLK/SCK".
			Changed references of "RDCFGN" to "TSALLN".
			Changed references of "TDO/RDDATA" to "TDO".
		Architecture	Updated text in Ripple Mode section.
			Added information to Global Set/Reset.
			Added information for Spread Spectrum Clocking
			Modified information for PLL/DLL Cascading. DLL to PLL is now supported.
			Modified AIL Block text and figure.
			Modified Figure 2-20 DDR/Shift Register Block.
			Added Information to Hot Socketing.
			Added new information for I/O Architecture Rules.
			Added information to SERDES Power Supply Sequencing Requirements.
		DC and Switching Characteristics	Added footnote to Hot Socketing Specifications table.
			Modified Initialization and Standby Supply Current table.
			Modified GSR Timing table.
			Modified sysCLOCK DLL Timing table to include I_{DUTY}.
			Deleted Readback Timing information from sysCONFIG Port Timing table.
			Modified data in External Switching Characteristics table.
		Pin Information	Added information to the Signal Descriptions table for HDC/SI, LDCN/SCS.
			Added footnote to Signal Descriptions table.
			Modified Description for signal BUSYN/RCLK/SCK.
			Modified data in Pin Information Summary and device-specific Pinout Information tables.